

**Amendments to the Claims**

Please cancel Claim 12.

Please amend Claim 1, 2 and Claim 10 as set forth below. This listing of claims will replace all prior versions and listing of claims in the application.

**List of Claims**

1. (currently amended) An imaging device comprised of:
  - a photon source for generating a photon reflection from a target,
  - a detector array for producing a detector array output signal in response to said photon reflection,
  - a multilayer processing module for the receiving of said detector array output signal,
  - said processing module comprised of at least two stacked layers wherein each of said at least two stacked layers are comprised of at least one integrated circuit chip for the processing of said received detector array output signal wherein said detector array is bonded to a lateral surface of said processing module and substantially perpendicular to said at least two stacked layers and wherein said detector array is electrically connected to said at least one integrated circuit chip via a plurality of electrical connections disposed on said lateral surface of said processing module.
2. (currently amended) The imaging device of claim 1 wherein said lateral surface of said processing module includes at least one T-connect structure formed thereon for the electrical connection of said detector array ~~to of an external electronic device.~~
3. (previously presented) The imaging device of claim 1 further comprising circuit means for converting said processed detector array output signal into an electronic image.
4. (previously presented) The imaging device of claim 1 further comprising circuit means for converting said processed detector array output signal into a three-dimensional electronic image.

5. (previously presented) The imaging device of claim 1 wherein said photon source is a laser.
6. (previously presented) The imaging device of claim 1 wherein said photon source is a pulsed laser.
7. (previously presented) The imaging device of claim 1 further comprising beam-shaping optics for the focussing of said photon source upon said target.
8. (previously presented) The imaging device of claim 1 further comprising collection optics for the focussing of said reflected photons upon said detector array.
9. (previously presented) The imaging device of claim 1 wherein said detector array is an InGaAs detector array.
10. (currently amended) The imaging device of claim 1 wherein said detector array is bump bonded to said lateral surface of said processing module by means of at least one T-connect.
11. (previously presented) The imaging device of claim 1 wherein said detector array output signal is compared to a predetermined threshold using a comparator.
12. (cancelled)